



ABS AP163

Injection Molding Grade

Description

Very low Surface resistivity

Application

COG(Chip on glass) Tray for semiconductor

Properties	Test Condition	Test Method	Unit	Typical Value
Physical				
Specific Gravity		ASTM D792	-	1.06
Molding Shrinkage (Flow), 3.2mm		ASTM D955	%	0.4~0.7
Melt Flow Rate	220℃/10kg	ASTM D1238	g/10min	30
/lechanical				
Tensile Strength, 3.2mm		ASTM D638		
@ Yield	50mm/min		kg/cm ²	420
Tensile Elongation, 3.2mm		ASTM D638	• •	
@ Yield	50mm/min		%	
@ Break	50mm/min		%	>10
Flexural Strength, 3.2mm	15mm/min	ASTM D790	kg/cm ²	680
Flexural Modulus, 3.2mm	15mm/min	ASTM D790	kg/cm ²	21,000
IZOD Impact Strength, 6.4mm		ASTM D256		
(Notched)	23 ℃		kg·cm/cm	
	- 30 ℃		kg·cm/cm	
IZOD Impact Strength, 3.2mm		ASTM D256		
(Notched)	23 ℃		kg·cm/cm	45
	- 30 ℃		kg·cm/cm	
Rockwell Hardness	R-Scale	ASTM D785	-	98
Thermal				
Heat Deflection Temperature, 6.4mm		ASTM D648		
(Unannealed)	18.6kg		$^{\circ}$	83
	4.6kg		°C	
Vicat Softening Temperature		ASTM D1525		
	5kg, 50℃/h		$^{\circ}$	
Flammability	og, 00 o	UL94		
1.5mm			class	HB
3.0mm			class	HB
Relative Temperature Index		UL 746B		
Electrical			$^{\circ}$	60
Mechanical with Impact			Ĉ	60
Mechanical without Impact			r	60
lectrical				
Comparative Tracking Index(CTI)	Solution A	IEC 60112	Volts	
Surface Resistivity		IEC 60093	Ohm	2.3E+12
Volume Resistivity	23 ℃	ASTM D257	Ohm∙m	
Arc Resistance	23 ℃	ASTM D495	Ohm⋅cm	

Note) Typical values are only for material selection purpose, and variation within normal tolerances are for various colors.

Updated: 14-Jun-17

Values given should not be interpreted as specification and not be used for part or tool design.

All properties, except melt flow rate are measured on injection molulded specimens and after 48 hours storage at 23 °C, 50% relative humidty.

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Processing Guide (Injection Molding)

Processing Parameters		Unit	Value
Drying Temperature		$^{\circ}$	80
Drying Time		hrs	2 ~ 4
Minimum Moisture Content		%	0.01
Melt Temperature		${\mathbb C}$	210 ~ 240
Cylinder Temperature	Rear	${\mathbb C}$	180 ~ 200
	Middle	${\mathbb C}$	190 ~ 210
	Front	${\mathbb C}$	200 ~ 220
Nozzle Temperature		${\mathbb C}$	200 ~ 230
Mold Temperature		${\mathbb C}$	40 ~ 70
Back Pressure		kg/cm ²	5 ~ 15
Screw Speed		%	30 ~ 60

Note) Back Pressure & Screw Speed are only mentioned as general guidelines.

These may not apply or need adjustment in specific situations such as low shot sizes, thin wall molding and gas-assist molding.